

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) Flame retardant polyamide compound comprising a polyamide polymer having a weight-average molecular weight of at least 10,000 ~~10,000~~ g/mol, a halogen-free flame retardant and a polyamide oligomer having a weight-average molecular weight of at most 4000 g/mol ~~7500~~, and wherein the polyamide oligomer is a melt-processable semi-crystalline or amorphous polyamide, and wherein characterized in that the halogen-free flame retardant is a halogen-free phosphorous containing flame retardant.
2. (Original) Compound according to claim 1, wherein the polyamide oligomer is a polyamide with a melting temperature of at least 260°C.
3. (Previously Presented) Compound according to claim 1, wherein the polyamide oligomer is present in an amount of 0.1-30 weight %, relative to the total weight of polyamide.
4. (Previously Presented) Compound according to claim 1, wherein the halogen-free phosphorous containing flame retardant is a melamine based phosphorous compound.
5. (Previously Presented) Compound according to claim 1, wherein phosphorous containing flame retardant is present in an amount between 1 and 100 parts by weight, relative to a total amount of polyamide of 100 parts by weight.
6. (Currently Amended) Process for preparing a compound according to claim 1 comprising melt-mixing of a polyamide composition comprising a polyamide polymer having a weight-average molecular weight of at least 10,000 ~~10,000~~ g/mol, a polyamide oligomer having a weight-average molecular weight of at most 4000 g/mol ~~7500~~, and a halogen-free phosphorous containing flame retardant.
7. (Original) Process according to claim 6, wherein the polyamide polymer is a polyamide with a melting temperature of at least 260°C.

8. (Previously Presented) Process according to claim 6, wherein the polyamide oligomer has a melting temperature of at most 20°C above the melting temperature of the polyamide polymer.

9. (Previously Presented) Process according to claim 1, wherein the polyamide compound comprises a reinforcing component.

10. (Cancelled).

11. (Previously Presented) Molded part obtainable by melt-processing of a polyamide compound according to claim 1.

12. (New) Method of using a polyamide compound according to claim 1 comprising:
selecting the polyamide compound, and
preparing a molded part by melt-processing the polyamide compound.

13. (New) Flame retardant polyamide compound comprising a polyamide polymer having a weight-average molecular weight of at least 10,000 g/mol, a halogen-free flame retardant, and a polyamide oligomer having a weight-average molecular weight of at most 7500 g/mol, wherein the halogen-free flame retardant is a halogen-free phosphorous containing flame retardant, and wherein the content of flame retardant is above 25 parts by weight and the content of oligomer is above 10 parts by weight, relative to 100 parts by weight of polyamide.

14. (New) Compound according to claim 13, wherein the polyamide oligomer is a polyamide with a melting temperature of at least 260°C.

15. (New) Compound according to claim 13, wherein the polyamide oligomer is present in an amount of 0.1-30 weight %, relative to the total weight of polyamide.

16. (New) Compound according to claim 13, wherein the halogen-free phosphorous containing flame retardant is a melamine based phosphorous compound.

17. (New) Compound according to claim 13, wherein phosphorous containing flame retardant is present in an amount between 1 and 100 parts by weight, relative to a total amount of polyamide of 100 parts by weight.

18. (New) Process for preparing a compound according to claim 13 comprising melt-mixing of a polyamide composition comprising a polyamide polymer having a weight-average molecular weight of at least 10,000 g/mol, a polyamide oligomer having a weight-average molecular weight of at most 7500 g/mol, and a halogen-free phosphorous containing flame retardant.

19. (New) Process according to claim 18, wherein the polyamide polymer is a polyamide with a melting temperature of at least 260°C.

20. (New) Process according to claim 18, wherein the polyamide oligomer has a melting temperature of at most 20°C above the melting temperature of the polyamide polymer.

21. (New) Process according to claim 13, wherein the polyamide compound comprises a reinforcing component.

22. (New) Molded part obtainable by melt-processing of a polyamide compound according to claim 13.

23. (New) Method of using a polyamide compound according to claim 13 comprising:
selecting the polyamide compound, and
preparing a molded part by melt-processing the polyamide compound.

24. (New) Flame retardant polyamide compound consisting of:

- a. 70-99.9 parts by weight of a polyamide polymer having a weight-average molecular weight of at least 10,000 g/mol

- b. 0.1-30 parts by weight of a polyamide oligomer having a molecular weight of at most 7500 g/mol, whereby the total amount of a) + b) is 100 parts by weight
 - c. 1-100 parts by weight of a halogen-free phosphorous containing flame retardant
 - d. 0-100 parts by weight of a reinforcing agent
 - e. 0-25 parts by weight of at least one other component.
25. (New) Compound according to claim 24, wherein the polyamide oligomer is a polyamide with a melting temperature of at least 260°C.
26. (New) Compound according to claim 24, wherein the polyamide oligomer is present in an amount of 0.1-30 weight %, relative to the total weight of polyamide.
27. (New) Compound according to claim 24, wherein the halogen-free phosphorous containing flame retardant is a melamine based phosphorous compound.
28. (New) Compound according to claim 24, wherein phosphorous containing flame retardant is present in an amount between 1 and 100 parts by weight, relative to a total amount of polyamide of 100 parts by weight.
29. (New) Process for preparing a compound according to claim 24 comprising melt-mixing of a polyamide composition comprising a polyamide polymer having a weight-average molecular weight of at least 10,000 g/mol, a polyamide oligomer having a weight-average molecular weight of at most 7500 g/mol, and a halogen-free phosphorous containing flame retardant.
30. (New) Process according to claim 29, wherein the polyamide polymer is a polyamide with a melting temperature of at least 260°C.
31. (New) Process according to claim 29, wherein the polyamide oligomer has a melting temperature of at most 20°C above the melting temperature of the polyamide polymer.

32. (New) Process according to claim 24, wherein the polyamide compound comprises a reinforcing component.

33. (New) Molded part obtainable by melt-processing of a polyamide compound according to claim 24.

34. (New) Method of using a polyamide compound according to claim 24 comprising:
selecting the polyamide compound, and
preparing a molded part by melt-processing the polyamide compound.